



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SURFBOARDS®



THE BREADBOARDING MEDIUM FOR SURFACE MOUNT™

33000 SERIES APPLICATION SPECIFIC ADAPTERS

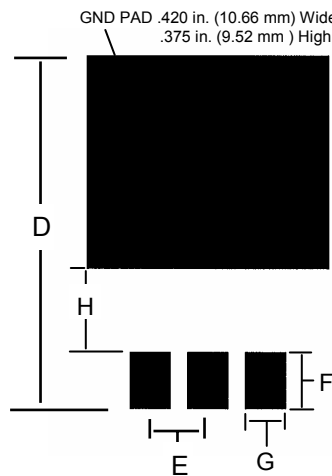
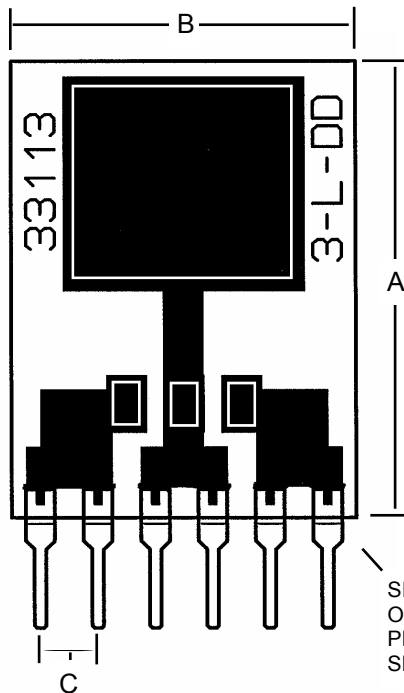
IDS33113

REV 1-2012

MODEL **33113**

FOR TO-263AB
3-LEAD D PACKAGE

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT



PINS ON .1 in. CENTERS PROVIDE COMPATIBILITY WITH BREADBOARDS AND SOCKETS. TWO PINS ARE PROVIDED FOR EACH DEVICE LEAD FOR GREATER CURRENT CAPACITY.

NOTE: CIRCUIT FOILS AND OUTPUT PINS MAY NOT BE SUITABLE FOR OPERATION AT HIGHEST RATED DEVICE CURRENT LEVELS. EXTREME TEMPERATURE RISE MAY RESULT IN FAILURE.

SINGLE-IN-LINE (SIP) PINS ON .1 in. CENTERS. TWO PER DEVICE LEAD. SEE PIN SPECS.

PIN SPECIFICATIONS / TOLERANCES

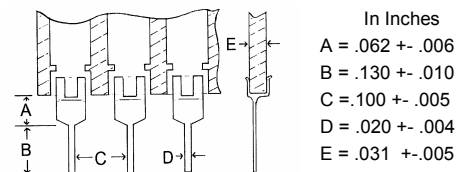


FIG.	INCHES	MM	NOTE:
A	.800	20.32	BOARD HEIGHT +/- .5mm .020in.
B	.600	15.24	BOARD WIDTH +/- .5mm .020in.
C	.100	2.54	SIP PIN SPACE +/- .20mm .008in.
D	.625	15.87	PAD (DEVICE) MAX
E	.100	2.54	DEVICE LEAD PITCH
F	.100	2.54	PAD LENGTH
G	.070	1.77	PAD WIDTH
H	.150	3.81	GAP



BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +/- .13mm .031in+-.005 in. Thick G-10 FR-4 Glass Epoxy or equivalent.
CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +/- .5mm .020in.

TOLERANCES: If not noted are +/- 20%. Nominal values are given. Controlling unit is Millimeters. Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

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